

●Features

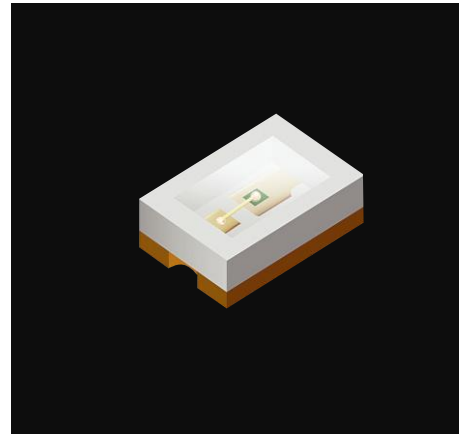
- Compact LED with reflector
- Die is located at the center of the package, achieving equivalent distribution of light emission.

●Size

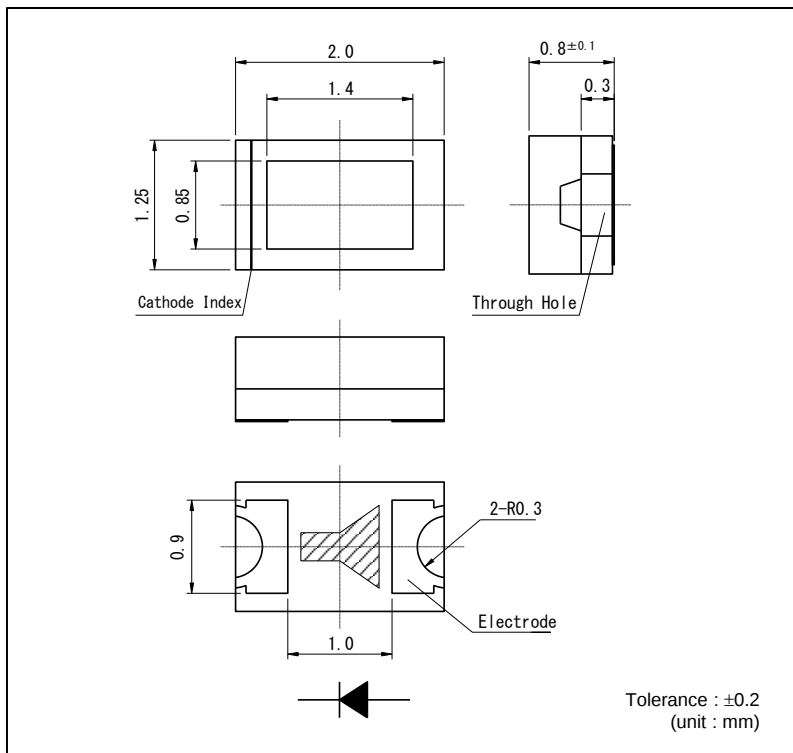
20125 (0805)
2.0 × 1.25mm (t=0.8mm)



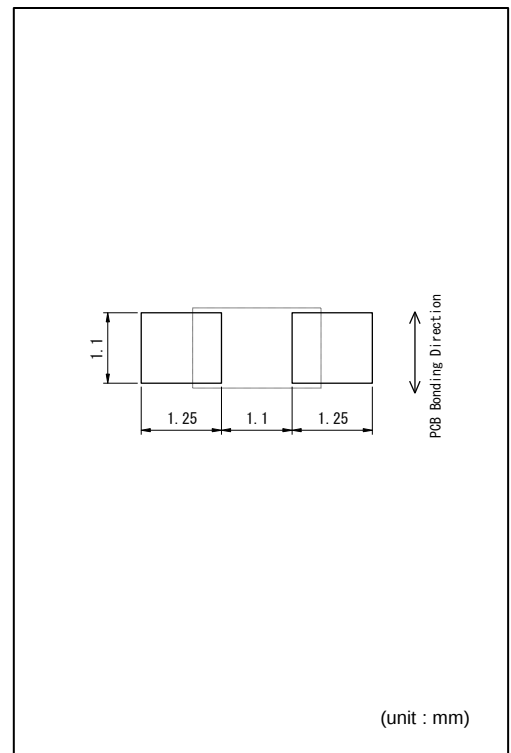
●Outline



●Dimensions



●Recommended Solder Pattern



●Specifications

Part No.	Chip Structure	Emitting Color	Absolute Maximum Ratings (Ta=25°C)						Electrical and Optical Characteristics (Ta=25°C)										
			Power Dissipation	Forward Current	Peak Forward Current	Reverse Voltage	Operating Temp.	Storage Temp.	Forward Voltage V _F		Reverse Current I _R		Dominant Wavelength λ _D			Luminous Intensity I _V			
			P _D (mW)	I _F (mA)	I _{FP} (mA)	V _R (V)	Topr(°C)	Tstg(°C)	Typ.	I _F (mA)	Max.	V _R (V)	Min.*2 (nm)	Typ.	Max.*2 (nm)	I _F (mA)	Min. (mcd)	Typ.	I _F (mA)
SML-M13VT	AlGaInP	Red	75	30	100* ¹	5	-40 to +85	-40 to +100	2.0	20	10	5	625	630	635	20	40	75	20
SML-M13UT													615	620	625		63	120	
SML-M13DT													602	605	608		100	200	
SML-M13YT		Yellow	81	30	100* ¹	5	-40 to +85	-40 to +100	2.2	20	10	5	587	590	593	20	100	160	20
SML-M13MT		Yellowish Green											569	572	575		25	45	
SML-M13PT		Green											557	560	563		6.3	16	

*1 : Duty 1/10, 1kHz *2 : Reference

●Electrical Characteristics Curves

Fig.1 Forward Current - Forward Voltages

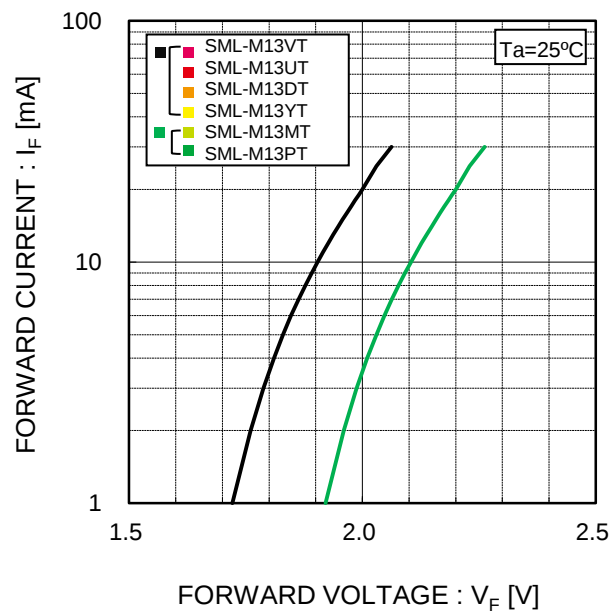


Fig.2 Luminous Intensity - Atmosphere Temperature

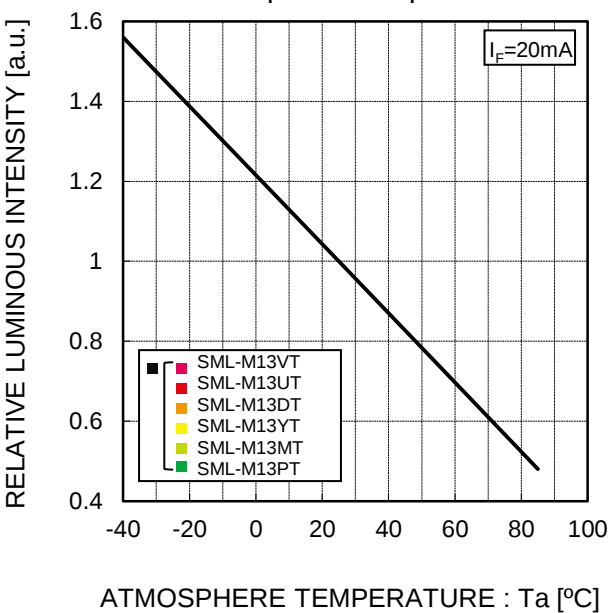


Fig.3 Luminous Intensity - Forward Current

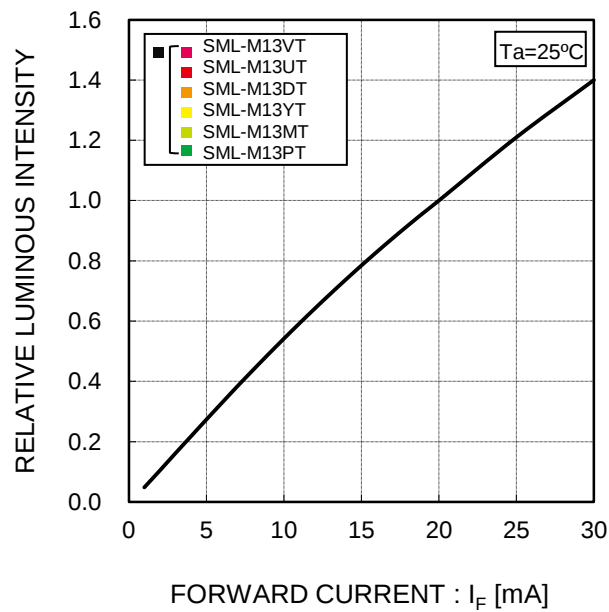
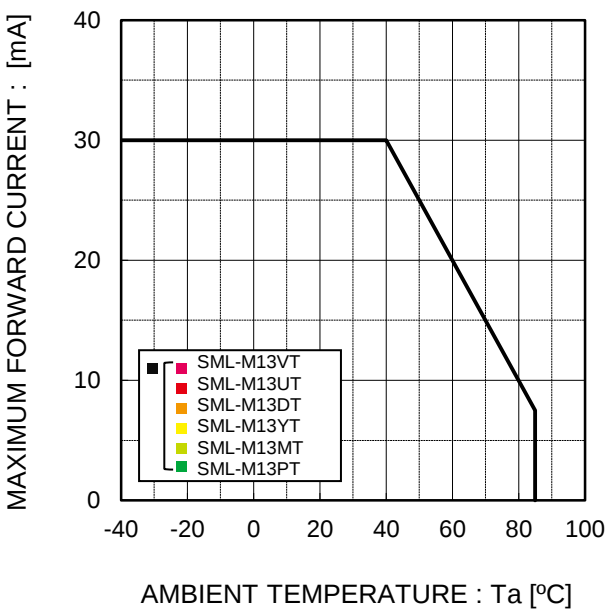
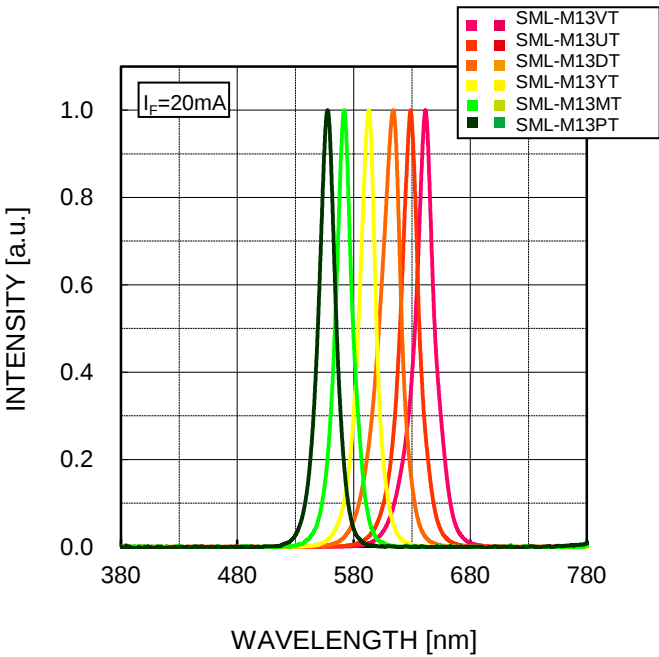


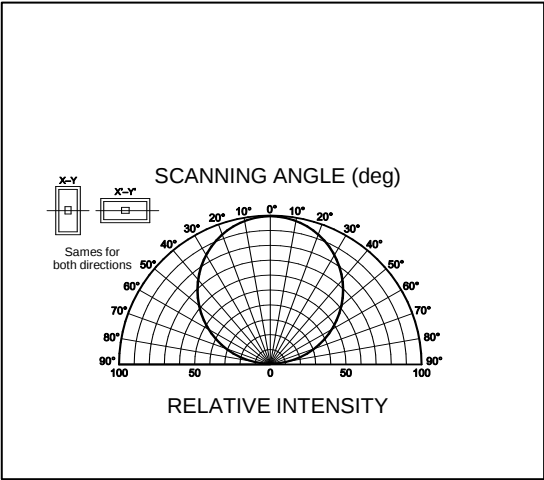
Fig.4 Derating



●Spectrum Data



●Viewing Angle



* Please take this data as a reference data for the samples are measured randomly.
* The data is relativized for each color. It is NOT to show the spectrum peaks are equal.

●Rank Reference of Brightness

Red(V, U)

(Ta=25°C, I_F=20mA)

Rank	K	L	M	N	P	Q	R	S	T	U	V	W	X
I _v (mcd)	4.0 to 6.3	6.3 to 10	10 to 16	16 to 25	25 to 40	40 to 63	63 to 100	100 to 160	160 to 250	250 to 400	400 to 630	630 to 1000	1000 to 1600
SML-M13VT													
SML-M13UT													

Orange(D)

(Ta=25°C, I_F=20mA)

Rank	K	L	M	N	P	Q	R	S	T	U	V	W	X
I _v (mcd)	4.0 to 6.3	6.3 to 10	10 to 16	16 to 25	25 to 40	40 to 63	63 to 100	100 to 160	160 to 250	250 to 400	400 to 630	630 to 1000	1000 to 1600
SML-M13DT													

Yellow(Y)

(Ta=25°C, I_F=20mA)

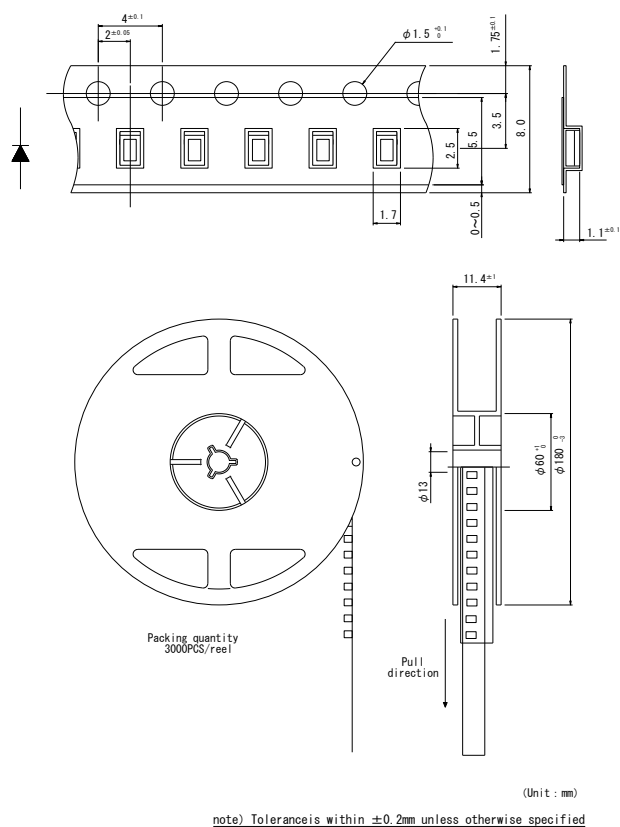
Rank	K	L	M	N	P	Q	R	S	T	U	V	W	X
I _v (mcd)	4.0 to 6.3	6.3 to 10	10 to 16	16 to 25	25 to 40	40 to 63	63 to 100	100 to 160	160 to 250	250 to 400	400 to 630	630 to 1000	1000 to 1600
SML-M13YT													

Green(M, P)

(Ta=25°C, I_F=20mA)

Rank	K	L	M	N	P	Q	R	S	T	U	V	W	X
I _v (mcd)	4.0 to 6.3	6.3 to 10	10 to 16	16 to 25	25 to 40	40 to 63	63 to 100	100 to 160	160 to 250	250 to 400	400 to 630	630 to 1000	1000 to 1600
SML-M13MT													
SML-M13PT													

●Taping



●Part No. Construction

(Special classification code)

S M L — **M 1 3** **U** **T** **T 8 6** **S**

Series name Package name Chip Type Emitting Color Resin Color Taping Specifications Rank sign (Brightness Rank)*

Package name	Chip Type	Emitting Color	Resin Color	Taping Specifications	Rank sign (Brightness Rank)*
1	Standard Type	V Red:630nm	T Transparent Colorless	T86 Cathode at sprocket hole side	
2		U Red:620nm	W MilkyWhite	T87 Reverse of T86	
3	High Brightness Type	D Orange:605nm		1 For white LED and pastel color, cathode at sprocket hole side	
		Y Yellow:590nm			
		W Yellow:587nm			
		M Yellowish-Green:572nm			
		P Green:560nm			

* Concerning the Brightness rank
• Please refer to the rank chart above for luminous intensity classification.
• Please refer to the Specification sheet for color classification.
• Part name is individual for each rank.
• When shipped as sample, the part name will be a representative part name.
General products are free of ranks. Please contact sales if rank appointment is needed.
• Please refer to the Specification sheet about Taping specification.

●Packing Specification

ROHM LED products are being shipped with desiccant (silica gel) concluded in moisture-proof bags.

Pasting the moisture sensitive label on the outer surface of the moisture-proof bags or enclosing the humidity indication card inside the bag is available upon request.

Please contact the nearest sales office or distributor if necessary.

●Attention Points In Handling

This product was developed as a surface mount LED especially suitable for reflow soldering.
Please take care of following points when using this device.

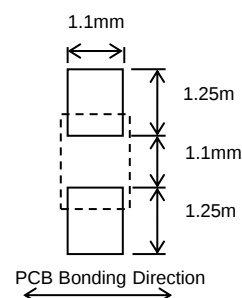
1.DESIGNING OF PCB

As for a recommendable solder pattern, Please refer to Fig-1.

The size and direction of the pad pattern depend on the condition of the PCB.

Thorough design review is recommended before the final designing.

{ This product of structured with rear/bottom electrode to be soldered.
 The formation of solder fillet is not guaranteed due to its electrode shape }



(Fig-1)

2.MOUNTING

This LED was designed to fit various mounting machines.

A round type nozzle is recommended for a hollow lens surface.

3.SOLDERING

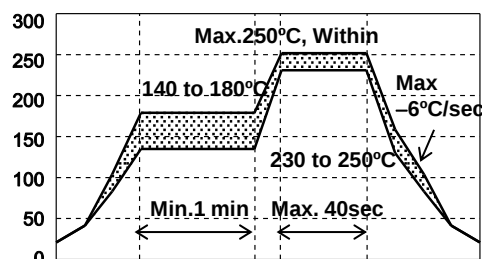
LED products do not contain reinforcement materials such as glass fillers. Therefore, thermal stress by soldering greatly influences its reliability.

The temperature condition for reflow soldering should therefore be set up according to the characteristic of this products. (See Fig.2)

Number of reflow process shall be max 2 times and these process shall be performed in a row.

Cooling process to normal temp.

Cooling process to normal temp. Shall be required between first and second soldering process



(Fig-2)

4.WASHING

Please note the following points when washing is required after soldering.

4-1) WASHING SOLVENT

Isopropyl alcohol or other alcohol solvent is recommendable.

4-2) TEMPERATURE

Below 30°C, immersion time ; within 3 minutes.

4-3) ULTRA SONIC WASHING

Below 15W/1 litter of solvent tub or less.

4-4) COOLING

Below 100°C within 3 minutes.

5.EROSION GAS

Utilization in erosion gas atmosphere may degenerate the plating surface which might cause deterioration of solder strength, optical characteristics, or functions.

Please take precautions against occurrence of gas from the surrounding parts on the occasion of custody, and also after mounted on circuit board.

6.STORAGE

At reflow soldering, the reliability of this product is often influenced by moisture absorption so we apply the packaging with moisture proof for better condition is use, please also note that

6-1) Not to be opened before using.

6-2) To be kept in our moisture proof packaging with some desiccant (SILICA GEL) after opening it

To be baked in case the SILICAGEL indicator changed its color from either blue to clear or green to pink.

6-3) Please use within 72 hours after the package was opened. (Condition at 30°C, max.70%Rh.)

In case it is not used within 72 hours, please put it back into our packaging.

6-4) BAKING

Please bake under reel condition at 60°C, 40 to 48 hours (max.20%Rh) after un-sealing.

While baking is done, the reel and emboss tape may be easily deformed.

Please be careful not to give any stress.

7.LIFE TIME

This product will cause reduction of luminous intensity depending on the using conditions and environmental

Please inquire our sales contact if long life time is required on your application.

Notes

- 1) The information contained herein is subject to change without notice.
- 2) Before you use our Products, please contact our sales representative and verify the latest specifications :
- 3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors.
Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Products beyond the rating specified by ROHM.
- 4) Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.
- 5) The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use of such technical information.
- 6) The Products are intended for use in general electronic equipment (i.e. AV/OA devices, communication, consumer systems, gaming/entertainment sets) as well as the applications indicated in this document.
- 7) The Products specified in this document are not designed to be radiation tolerant.
- 8) For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative : transportation equipment (i.e. cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.
- 9) Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters.
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- 11) ROHM has used reasonable care to ensure the accuracy of the information contained in this document. However, ROHM does not warrant that such information is error-free, and ROHM shall have no responsibility for any damages arising from any inaccuracy or misprint of such information.
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